

# Isc N-Channel MOSFET Transistor

# MDD1051RH

**• FEATURES**

- With To-252(DPAK) package
- Low input capacitance and gate charge
- Low gate input resistance
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

**• APPLICATIONS**

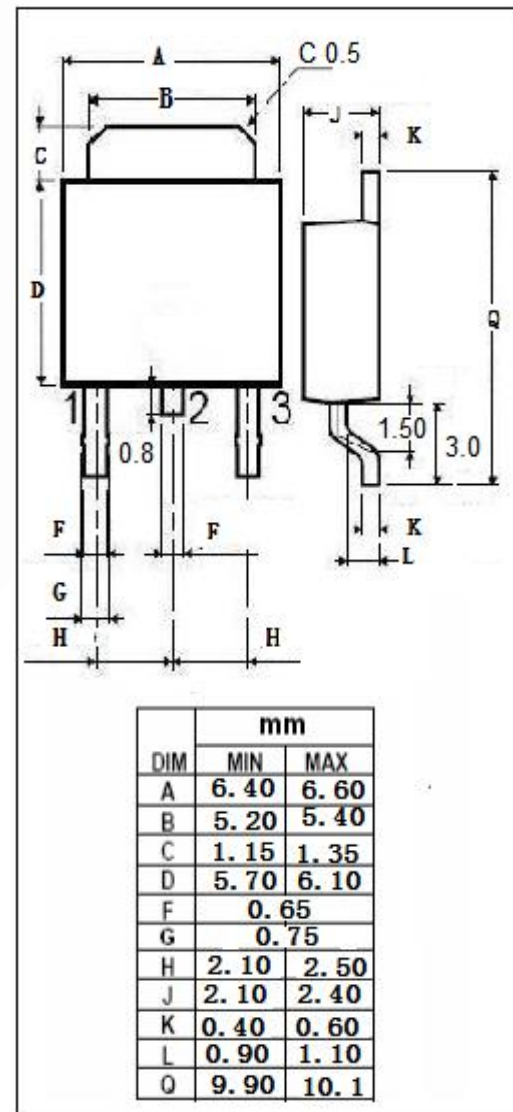
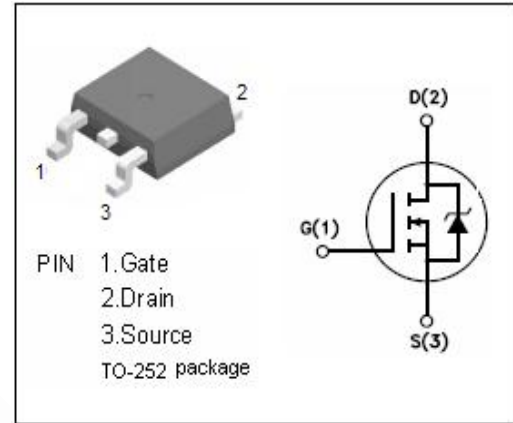
- Switching applications

**• ABSOLUTE MAXIMUM RATINGS(T<sub>a</sub>=25°C)**

SYMBOL	PARAMETER	VALUE	UNIT
V <sub>DSS</sub>	Drain-Source Voltage	150	V
V <sub>GSS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current-Continuous@T <sub>c</sub> =25°C T <sub>c</sub> =100°C	28 18	A
I <sub>DM</sub>	Drain Current-Single Pulsed	110	A
P <sub>D</sub>	Total Dissipation @T <sub>c</sub> =25°C T <sub>c</sub> =100°C	70 28	W
T <sub>ch</sub>	Max. Operating Junction Temperature	150	°C
T <sub>stg</sub>	Storage Temperature	-55~150	°C

**• THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	MAX	UNIT
R <sub>th(ch-c)</sub>	Channel-to-case thermal resistance	1.8	°C/W
R <sub>th(ch-b)</sub>	Thermal resistance junction-pcb max	50	°C/W



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**ELECTRICAL CHARACTERISTICS**

T<sub>C</sub>=25°C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V; I <sub>D</sub> = 0.25mA	150			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = ±20V; I <sub>D</sub> =0.25mA	1.2		3.2	V
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> = 10V; I <sub>D</sub> =20A		37	46	mΩ
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±20V; V <sub>DS</sub> = 0V			±0.1	μA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> = 120V; V <sub>GS</sub> = 0V			1	μA
V <sub>SDF</sub>	Diode forward voltage	I <sub>SD</sub> =20A, V <sub>GS</sub> = 0 V			1.3	V